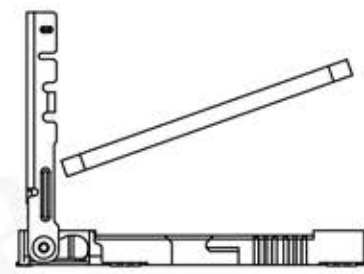
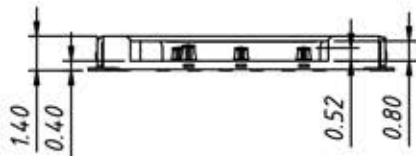
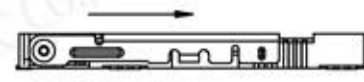


Material:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: C5210, Plated 50u" Ni
 Overall Contact All Au 1U.
 Shell: SUS. All Ni 30U/MIN.



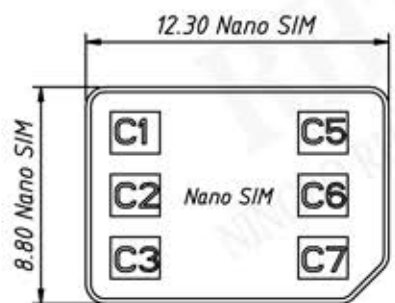
STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



SIM Card	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

Electrical:
 Current Rating: 0.5A
 Voltage Rating: 5V AC/DC
 Ambient Temperature Range: -40oC ~ +85oC
 Storage Temperature Range: -40oC ~ +85oC
 Ambient Humidity Range: 95% R.H. Max.
 Contact Resistance: 80mΩ Max.
 Insulation Resistance: 100MΩ Min./100V DC
 Mating Cycles: 10000 Insertions.
 Reflow peak temp: 260oC ±5oC, 3~5 s

PCB LAYOUT
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

UNITS:mm	SHEET SIZE:A4		SCALE: ---
> 0~ 3	> 3~ 18	> 18~ 50	> 50~ 120
± 0.12	± 0.15	± 0.3	± 0.5